IEEE EDS Fellows Elected 2022

Since 1963, IEEE has acknowledged those individuals who have contributed to the advancement of engineering science and technology. The honor of Fellow is bestowed on the recipient who has had an extraordinary record of accomplishments in any of the IEEE fields of interest. To learn more about the IEEE Fellow Program: https://www.ieee.org/membership/fellows/index.html.

Congratulations to the 25 EDS members elected to IEEE Grade of Fellow in 2022.

Lay-kee Ang - for contributions to electron emission and space charge effects in nanodiode and quantum materials

Anirban Bandyopadhyay - for leadership in silicon RF-SOI technologies

Seth Bank - for contributions to the growth of optoelectronic materials by molecular beam epitaxy
Subhashish Bhattacharya - for contributions to power conversion systems and active power filters

Zhihong Chen - for contributions to the understanding and applications of low-dimensional nanomaterials

Tarek El-bawab - for contributions to the definition, recognition, accreditation criteria, and program development of modern network-engineering education

Edmundo Gutierrez - for contributions to education and infrastructure in the field of electron devices in Latin America
Tony Heinz - for contributions to spectroscopic techniques, nanophotonics, and optical nanomaterials

David Horsley - for development of micro-electromechanical systems for ultrasonic transduction

Kevin Kelly - for contributions to compressive imaging

Sarah Kurtz - for contributions to photovoltaic devices and systems reliability

Ioannis Kymissis - for contributions to thin-film electronics for displays and sensors
Hang-ting Lue - for contributions to charge-trapping memories and 3D NOR flash

Philip Neudeck - for contributions to silicon carbide electronics and crystal growth

Anh-vu Pham - for contribution to organic packaging technologies

Eric Pop - For contributions to phase-change memory, and to the thermal science of nanomaterials and nanoscale transistors
Chuan Seng Tan - for contributions to wafer bonding technology for 3D packaging and integration

Florian Solzbacher - for the development of tools enabling applied and translational neuroscience and neural engineering

Nobuyuki Sugii - for contributions to fully depleted silicon-on-insulator technology

Tetsuzo Ueda - for contributions to III-V compound semiconductor technologies
Daniel Van Der Weide - for contributions to ultrafast terahertz electronics and biomedical applications of microwave technologies

Huili Grace Xing - for contributions to GaN high-electron-mobility transistors

(Jianhua) J. Joshua Yang - for contributions to resistive switching materials in memory and neuromorphic computing

Euisik Yoon - for contributions to bio-microelectromechanical systems (BioMEMS) technologies for optoelectrical neural interfaces and microfluidic biochips
Carl Zetterling - for contributions to silicon carbide devices